



General Description

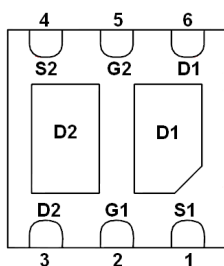
AFP2911W, P-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge.

These devices are particularly suited for low voltage power management, such as smart phone and notebook computer and other battery powered circuits, and low in-line power loss are needed in commercial industrial surface mount applications.

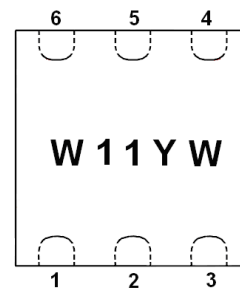
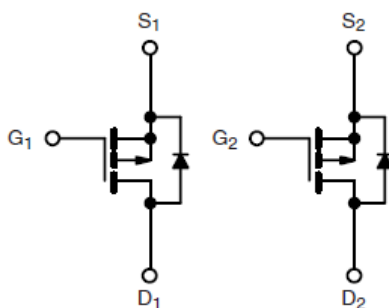
Features

- $I_D = -4.5A, R_{DS(ON)} = 80m\Omega @ V_{GS} = -4.5V$
- $I_D = -3.8A, R_{DS(ON)} = 105m\Omega @ V_{GS} = -2.5V$
- $I_D = -2.5A, R_{DS(ON)} = 145m\Omega @ V_{GS} = -1.8V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- DFN2X2-6L package design

Pin Description (DFN2X2-6L)



BOTTOM VIEW



TOP VIEW

Application

- Load Switch
- Portable Equipment
- Battery Powered System

Pin Define

| Pin | Symbol | Description |
|-----|--------|-------------|
| 1 | S1 | Source1 |
| 2 | G1 | Gate1 |
| 3 | D2 | Drain2 |
| 4 | S2 | Source2 |
| 5 | G2 | Gate2 |
| 6 | D1 | Drain1 |

Ordering Information

| Part Ordering No. | Part Marking | Package | Unit | Quantity |
|-------------------|--------------|-----------|-------------|----------|
| AFP2911WFN226RG | W11YW | DFN2X2-6L | Tape & Reel | 4000 EA |

※ W11 parts code

※ Y year code

※ W week code (A ~ Z = 1 ~ 26 / a ~ z = 27 ~ 52)

※ AFP2911WFN226RG : 7" Tape & Reel ; Pb- Free ; Halogen- Free



Absolute Maximum Ratings

(T_A=25°C Unless otherwise noted)

| Parameter | Symbol | Typical | Unit |
|---|------------------|----------------------|------|
| Drain-Source Voltage | V _{DSS} | -20 | V |
| Gate –Source Voltage | V _{GSS} | ±12 | V |
| Continuous Drain Current(T _J =150°C) | I _D | T _A =25°C | -4.5 |
| | | T _A =70°C | -3.8 |
| Pulsed Drain Current | I _{DM} | -12 | A |
| Continuous Source Current(Diode Conduction) | I _S | -1.6 | A |
| Power Dissipation | P _D | T _A =25°C | 6.5 |
| | | T _A =70°C | 4.2 |
| Operating Junction Temperature | T _J | 150 | °C |
| Storage Temperature Range | T _{STG} | -55/150 | °C |
| Thermal Resistance-Junction to Ambient | R _{θJA} | 120 | °C/W |

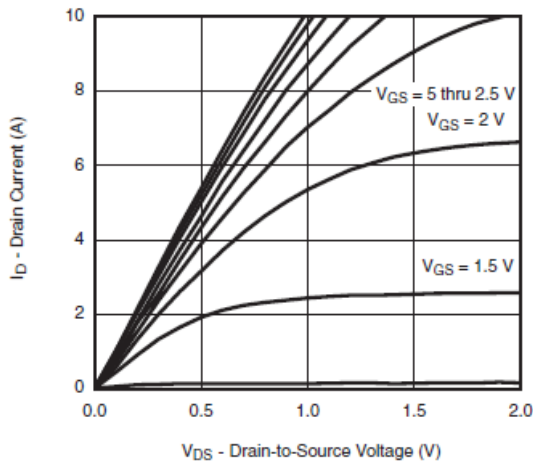
Electrical Characteristics

(T_A=25°C Unless otherwise noted)

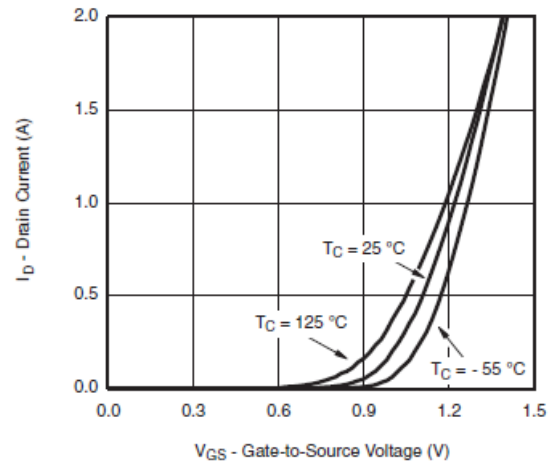
| Parameter | Symbol | Conditions | Min. | Typ | Max. | Unit |
|---------------------------------|----------------------|--|------|-------|------|------|
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V _{(BR)DSS} | V _{GS} =0V, I _D =-250uA | -20 | | | V |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =-250uA | -0.3 | | -0.8 | |
| Gate Leakage Current | I _{GSS} | V _{DS} =0V, V _{GS} =±12V | | | ±100 | nA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =-16V, V _{GS} =0V | | | -1 | uA |
| | | V _{DS} =-16V, V _{GS} =0V T _J =85°C | | | -30 | |
| On-State Drain Current | I _{D(on)} | V _{DS} ≤ -5V, V _{GS} =-4.5V | -8 | | | A |
| | | V _{DS} ≤ -5V, V _{GS} =-2.5V | -3 | | | |
| Drain-Source On-Resistance | R _{DS(on)} | V _{GS} =-4.5V, I _D =-4.5A | | 60 | 80 | mΩ |
| | | V _{GS} =-2.5V, I _D =-3.8A | | 80 | 105 | |
| | | V _{GS} =-1.8V, I _D =-2.5A | | 115 | 145 | |
| Forward Transconductance | g _{FS} | V _{DS} =-5V, I _D =-2.8A | | 6.5 | | S |
| Diode Forward Voltage | V _{SD} | I _S =-1.25A, V _{GS} =0V | | -0.75 | -1.3 | V |
| Dynamic | | | | | | |
| Total Gate Charge | Q _g | V _{DS} =-10V, V _{GS} =-4.5V I _D ≡-3.5A | | 5 | 10 | nC |
| Gate-Source Charge | Q _{gs} | | | 0.85 | | |
| Gate-Drain Charge | Q _{gd} | | | 1.5 | | |
| Input Capacitance | C _{iss} | V _{DS} =-10V, V _{GS} =0V f=1MHz | | 375 | | pF |
| Output Capacitance | C _{oss} | | | 80 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 60 | | |
| Turn-On Time | t _{d(on)} | V _{DD} =-10V, R _L =2.85Ω I _D ≡-3.5A, V _{GEN} =-4.5V R _G =1Ω | | 15 | 25 | ns |
| | t _r | | | 36 | 60 | |
| Turn-Off Time | t _{d(off)} | | | 25 | 50 | |
| | t _f | | | 15 | 25 | |



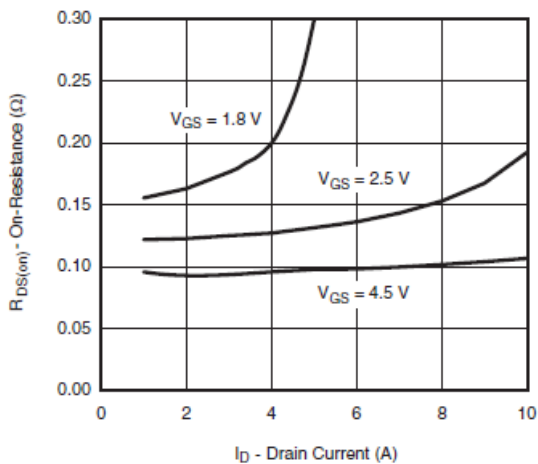
Typical Characteristics



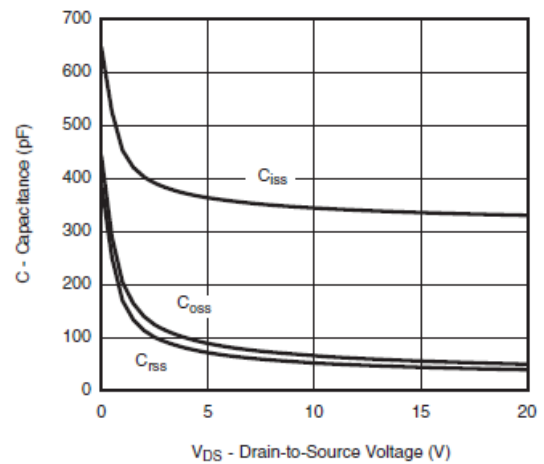
Output Characteristics



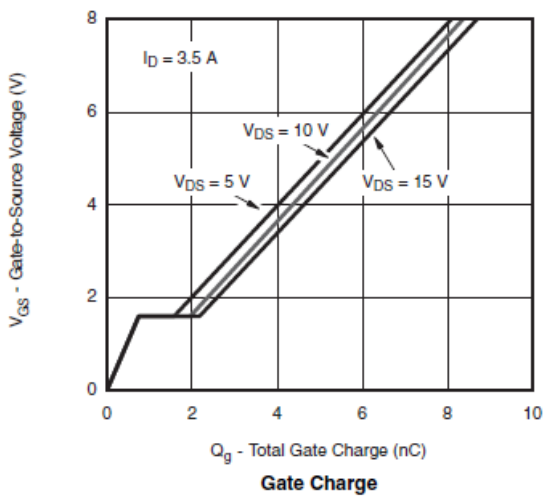
Transfer Characteristics



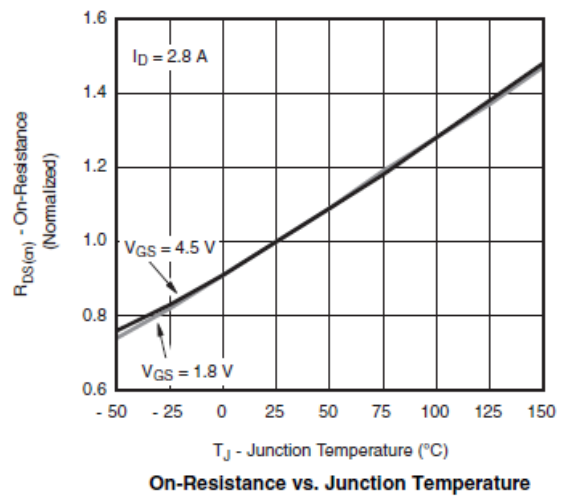
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



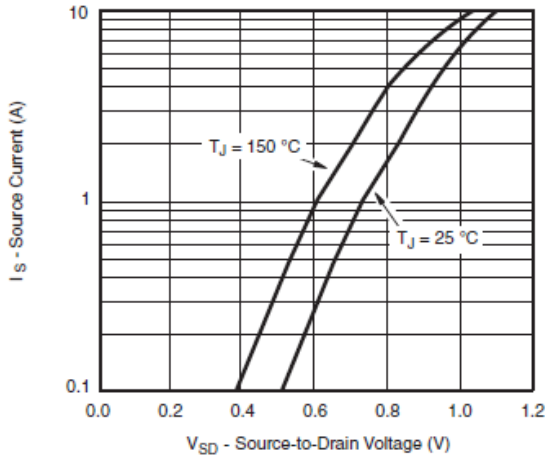
Gate Charge



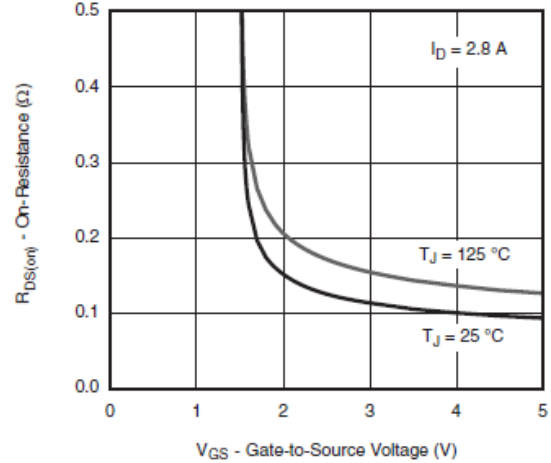
On-Resistance vs. Junction Temperature



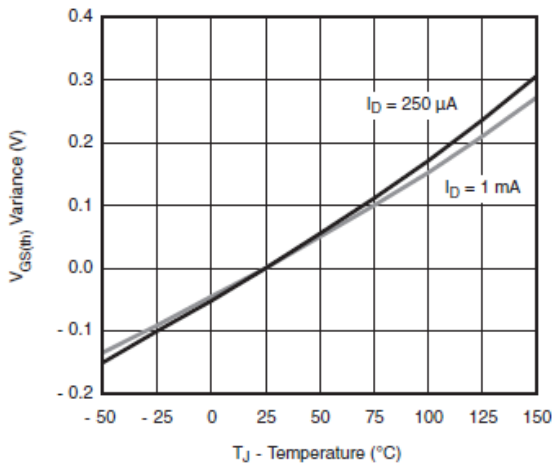
Typical Characteristics



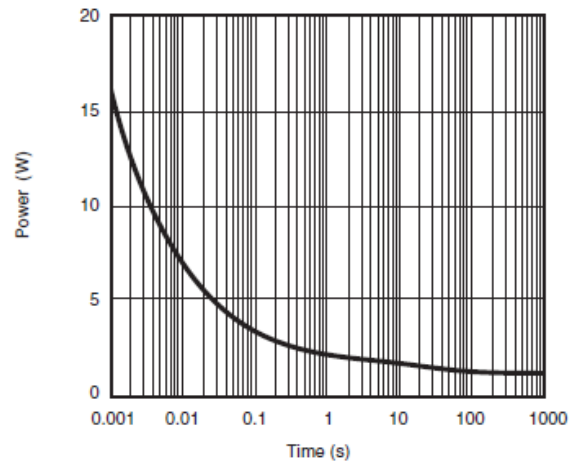
Source-Drain Diode Forward Voltage



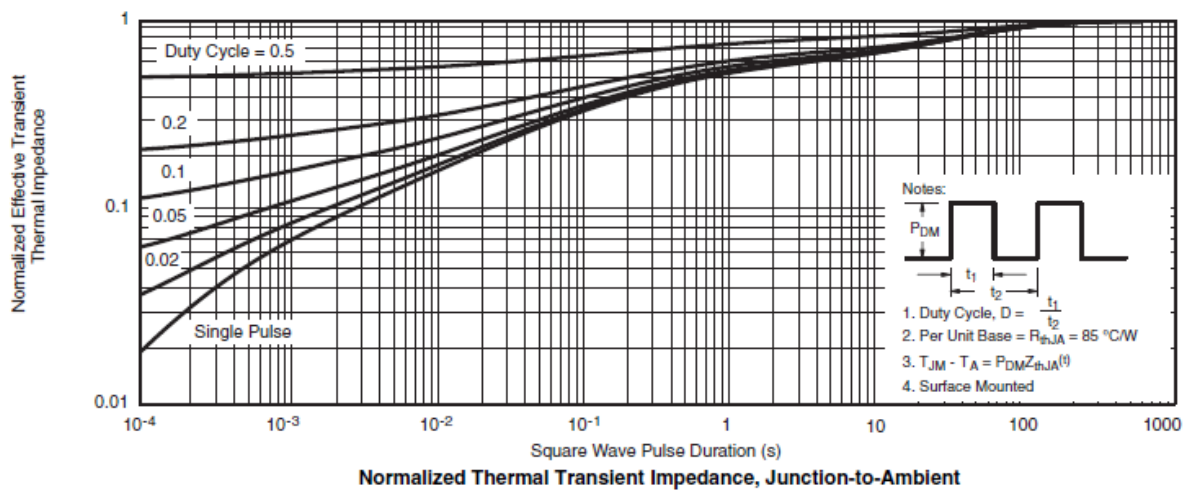
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

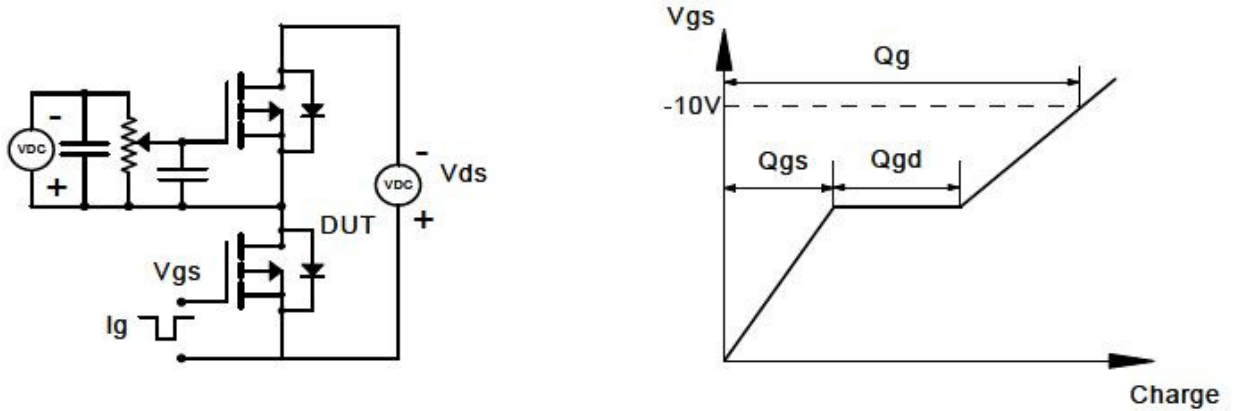


Normalized Thermal Transient Impedance, Junction-to-Ambient

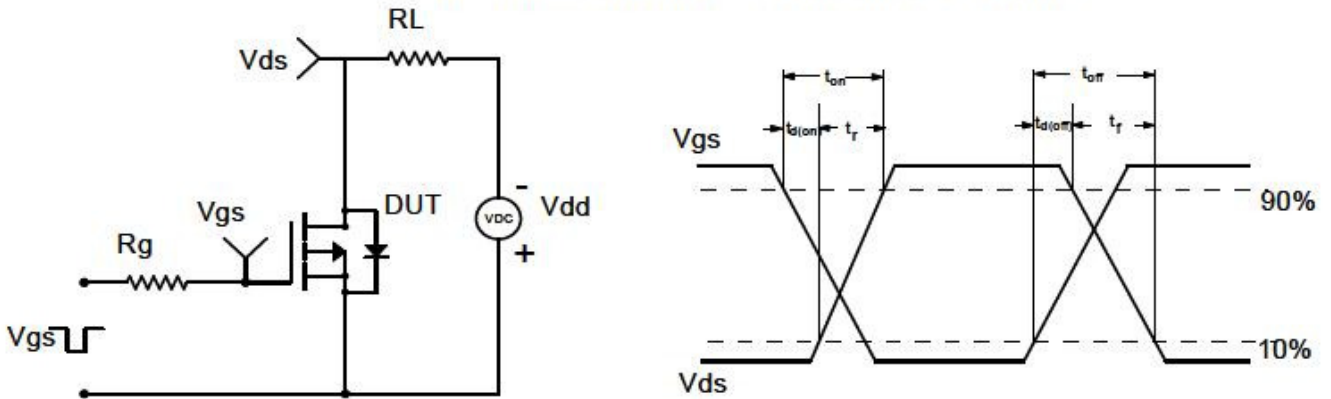


Typical Characteristics

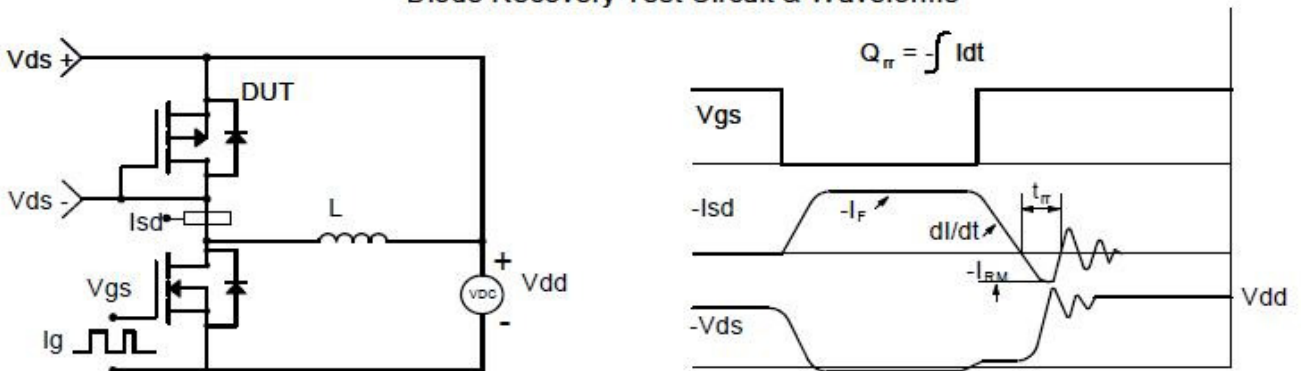
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

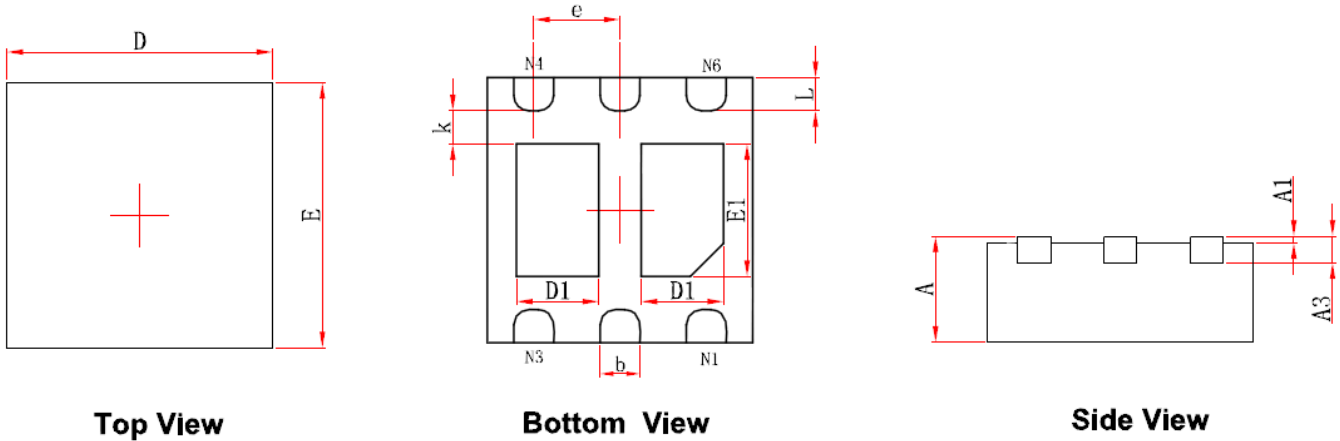


Diode Recovery Test Circuit & Waveforms





Package Information (DFN2X2-6L)



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------------|----------------------|-------------|
| | Min. | Max. | Min. | Max. |
| A | 0.700/0.800 | 0.800/0.900 | 0.028/0.031 | 0.031/0.035 |
| A1 | 0.000 | 0.050 | 0.000 | 0.002 |
| A3 | 0.203REF. | | 0.008REF. | |
| D | 1.924 | 2.076 | 0.076 | 0.082 |
| E | 1.924 | 2.076 | 0.076 | 0.082 |
| D1 | 0.520 | 0.720 | 0.020 | 0.028 |
| E1 | 0.900 | 1.100 | 0.035 | 0.043 |
| k | 0.200MIN. | | 0.008MIN. | |
| b | 0.250 | 0.350 | 0.010 | 0.014 |
| e | 0.650TYP. | | 0.026TYP. | |
| L | 0.174 | 0.326 | 0.007 | 0.013 |

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